



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2814
Examiner: Phat X. Cao

In re PATENT APPLICATION of:

Applicant(s): Nobuhisa KUMAMOTO et al.

Serial No.: 10/767,439

Filing date: January 30, 2004

For: PROCESS OF PRODUCING
SEMICONDUCTOR CHIP WITH
SURFACE INTERCONNECTION
AT BUMP (as amended)

Atty. ref.: AI 318 D1

**PETITION FOR
EXTENSION OF TIME**

August 22, 2006

Director of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Please extend the period for responding to the Office Action of March 22, 2006 by two months, and thus until August 22, 2006.

A remittance that includes the \$450 extension fee is being submitted concurrently. Should this remittance be accidentally missing or insufficient, though, any fees that may be needed can be charged to our Deposit Account number 18-0002.

Respectfully submitted,

Allen Wood
Registration No. 28,134
Customer number 23995
RABIN & BERDO, P.C.
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08/23/2006 SDEAB081 00000153 10767439

02 FC:1252

450.00 OP

FEE ENCLOSED: \$ 450.-
Please charge any further
fee to our Deposit Account
No. 18-0002

AW/ng